

**APPENDIX A**  
**"Clean" Version of Each Paragraph/Section/Claim**  
**37 C.F.R. § 1.121(b)(ii) and (c)(i)**

**CLAIMS (with indication of amended or new):**

B<sup>1</sup> 10. (Amended) The device of claim 6, wherein said passive component is disposed laterally between a respective pair of said fins.

B<sup>2</sup> 13. (Amended) An MCM device comprising:  
a flat thin insulation substrate having parallel top and bottom surfaces;  
a plurality of laterally displaced conductive vias extending between said top and bottom surfaces;  
a flip chip semiconductor die having top and bottom surfaces and having at least first and second electrodes on said top and bottom surfaces, wherein said first and second electrodes have contacts on said die bottom surface connected to respective ones of said plurality of vias; and  
an insulation cap covering said die and covering the top surface of said substrate, wherein said insulation cap has a peripheral rim which receives the outer peripheral edge of said substrate, and wherein the adjacent vertical surfaces of said peripheral rim and said outer peripheral edge of said substrate have cooperating projections and depressions to define a mold lock.

B<sup>3</sup> 20. (New) The device of claim 13, further comprising:  
at least one passive component which is beneath said insulation cap, wherein said at least one passive component has at least one dimension which is longer than its other dimensions, and wherein said at least one dimension is disposed perpendicular to said first surface of said substrate.

21. (New) The device of claim 20, wherein said insulation cap has a plurality of fins extending from a free surface thereof.

22. (New) The device of claim 21, wherein said at least one passive component is disposed laterally between a respective pair of said fins.